



Click here for the 3D model.

Dimensions	
L	4.5mm +/-0.3mm
W	3.5mm +/-0.4mm
Т	3.2mm +/-0.3mm
В	0.6mm +/-0.35mm

Packaging Specifications		
Packaging	T&R, 330mm, Plastic Tape	
Packaging Quantity	2200	

General Information		
Series	KONNEKT Comm U2J	
Style	KONNEKT	
Description	SMD, MLCC, KONNEKT, Ultra-Stable, Class I	
Features	High Density Packaging	
RoHS	Yes	
Termination	Tin	
AEC-Q200	No	
Chip Size	1812-2	
Shelf Life	78 Weeks	
MSL	1	

Specifications			
Capacitance	0.94 uF		
Capacitance Tolerance	5%		
Voltage DC	50 VDC		
Dielectric Withstanding Voltage	125 VDC		
Temperature Range	-55/+125°C		
Temperature Coefficient	U2J		
Dissipation Factor	0.1% 1 kHz 25C		
Aging Rate	0.1% Loss/Decade Hour		
Insulation Resistance	1.0638 GOhms		

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.